



Partial Translation of JP-A-2000-345031

[0009]

Now the present invention will be explained in detail. The polyamide resin to be employed in the present invention may be an aliphatic polyamide, such as polyamide 6, polyamide 46, polyamide 66, polyamide 610, polyamide 6/12, polyamide 11 or polyamide 12, an aromatic polyamide obtained from polyhexadamine terephthalamide, polyhexadamine isophthalamide, polytetramethylene isophthalamide, or m-xylenediamine and adipic acid, or a copolymer or a mixture thereof. Also the polyamide advantageously employable in the present invention is a polyamide resin having a melting point of from 160 to 320°C, and examples thereof include polyamide 6, polyamide 66, polyamide 6/66, polyamide 6/6T, polyamide 66/6T, and polyamide 66/6T/6I (wherein T stands for terephthalic acid, I stands for isophthalic acid, and / indicates copolymerization).

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[0020]

Example 1

In 100 parts by weight of a polyamide 6 resin (grade: UBE nylon 6 1015B), 3 parts by weight of black pigment master, 0.5 parts by weight of pentaerythritol

having a melting point of 260°C as polyhydric alcohol and 45 parts by weight of glass fibers were blended together by a two-shaft kneader TEX-44 of a diameter of 44 mm to obtain a desired polyamide composition. The obtained polyamide composition was subjected to measurement of a fluidity and a tensile strength of a test piece prepared by a DRI method, and an injection fusion strength was determined. Results are shown in Table 1. Also the obtained polyamide composition could be continuously molded, without clogging a filter of a hopper dryer of an injection molding machine.



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POLYAMIDE COMPOSITION HAVING GOOD FLUIDITY

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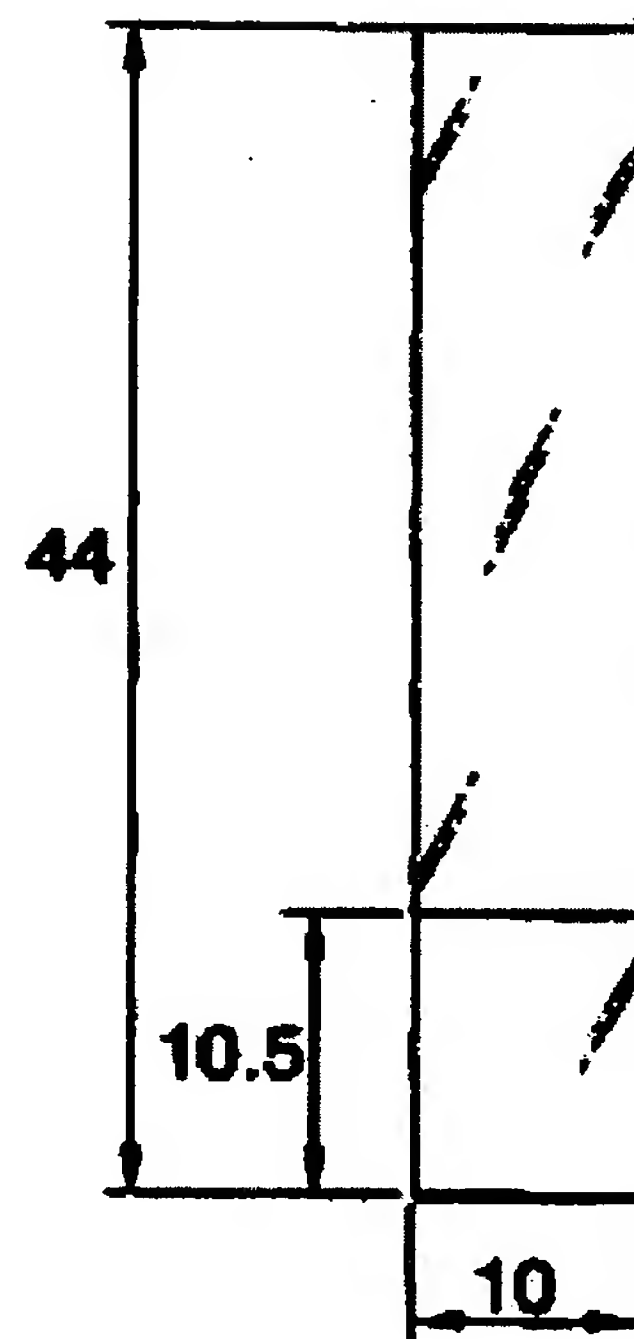
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Report a data error here**Abstract of JP2000345031**

PROBLEM TO BE SOLVED: To obtain a polyamide composition suppressed in scattering of a flow modifier and having good fluidity and good mechanical strengths by including a polyamide resin with a specified amount of a polyhydric alcohol having a melting point in a specified temperature range.

SOLUTION: This composition contains 100 pts.wt. polyamide resin and 0.005-5 pts.wt. polyhydric alcohol having a melting point of 150-280 deg.C. The composition may optionally contain a heat stabilizer, a weatherproofing agent, a crystallization accelerator, a mold release, an antistatic agent, a flame retardant, a coloring pigment, etc. The polyamide used is one having a melting point of

FIG. 1

160-320 deg.C such as polyamide 6, polyamide 66, polyamide 6/66, polyamide 6/6T, polyamide 66/6T, polyamide 66/6T/6I, or the like.

The polyhydric alcohol used is pentaerythritol, dipentaerythritol, trimethylolethane, or a mixture thereof.

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